

BONDING METHOD, BONDING APPARATUS AND SEALING MEANS

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ABSTRACT OF THE DISCLOSURE

10 A silicon substrate in which MEMS devices are formed
and a quartz substrate used to seal the silicon substrate
are tentatively bonded to each other. While the silicon
substrate and quartz substrate are being pressed using a
pressure jig, light having a wavelength that is absorbed
into the silicon substrate but not into the pressure jig
and quartz substrate is radiated from light sources to
15 the interface between the silicon substrate and quartz
substrate. Thus, the interface is heated and the silicon
substrate and quartz substrate are bonded.